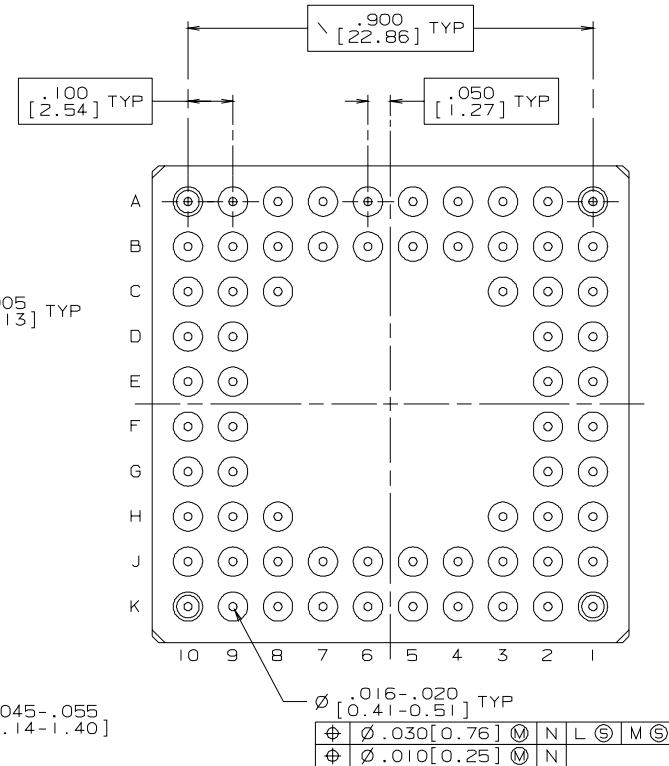
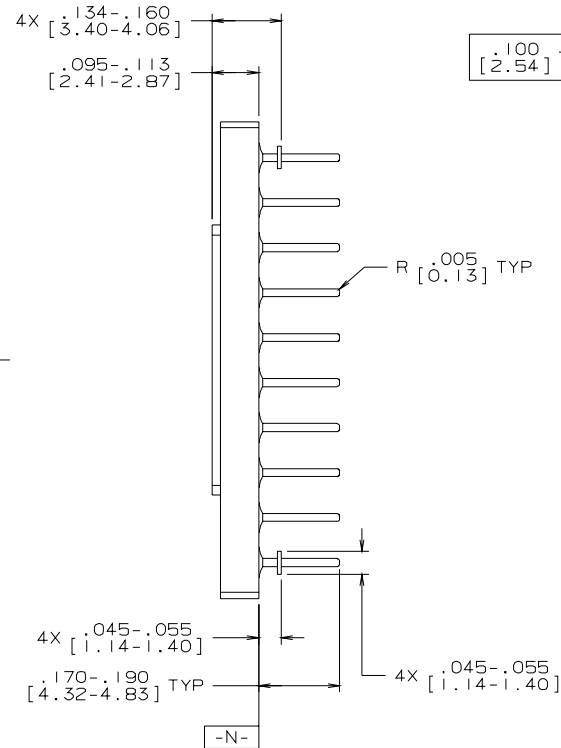
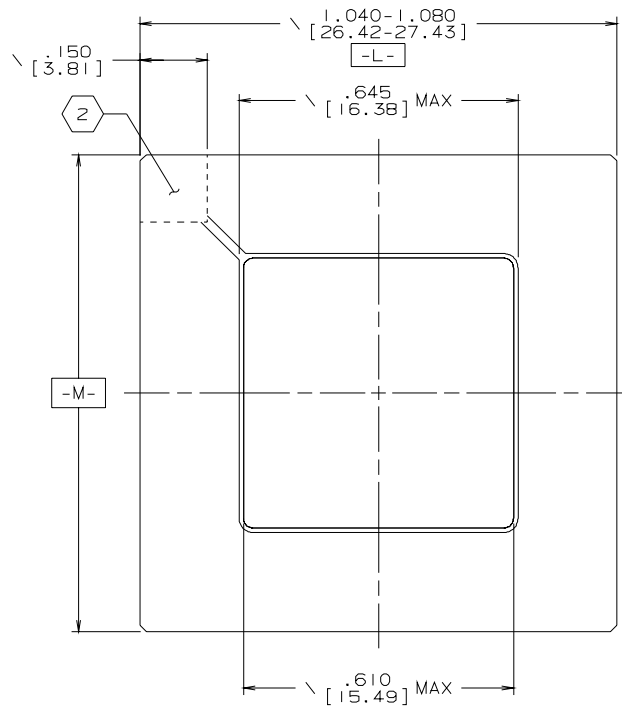


R E V I S I O N S				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	REVISE AND REDRAW:	09257	08/20/92	KES/



NOTES: UNLESS OTHERWISE SPECIFIED

- ALL EXPOSED METAL AND METALIZED SURFACES TO BE GOLD PLATED 50 MICROINCHES/ 1.27 MICROMETERS MINIMUM THICKNESS OVER 50-350 MICROINCHES/ 1.27-8.89 MICROMETERS THICKNESS OF NICKEL.

2. A-1 CORNER INDEX MAY BE ANY SHAPE WITHIN AREA SPECIFIED.

- REFERENCE JEDEC REGISTRATION MO-067, VARIATION AB, ISSUE A, DATED 5-87.

CONTROLLING DIMENSION: INCH			
APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION	
DRAWN <i>Ant Simen</i>	08/20/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090	
DFTG. CHK.		PIN GRID ARRAY, CERAMIC, CAVITY UP, 68 PIN	
ENGR. CHK.			
APPROVAL			
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	N/A	C	MKT-U68B
INCH [MM]	DO NOT SCALE DRAWING	SHEET	OF
		1	1